



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **L-0403-07** DATE: 3/24/04

Product Affected: Please see attachment

Date Effective: June 24, 2004

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
☐ Back Mark
☒ Date Code Prefix (Stepping) change from "P" to "PB"
☐ Other

Contact: Bimla Paul

Title: Quality Assurance Manager

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Attachment: ☒ Yes ☐ No

Samples: Available upon request

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
☐ Wafer Fabrication Process Fab location change to Hillsboro, Oregon (Fab 4) on selected Military Grade Logic products.
☐ Assembly Process
☐ Equipment
☐ Material The stepping will change from "P" to "PB". There is no change in data sheet specifications.
☐ Testing
☒ Manufacturing Site
☐ Data Sheet
☐ Other

RELIABILITY/QUALIFICATION SUMMARY:

Please see attachment for qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____

☐ *Approval for shipments prior to effective date.*

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____

DATE: _____



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ATTACHMENT - PCN #: L-0403-07

PCN Type: Fab Location Change

Data Sheet Change: None

Detail of Change: Fab location change to Hillsboro, Oregon (Fab 4) on these Military Grade Logic products.

The stepping will change from "P" to "PB". There is no change in data sheet specifications.

The following parts are affected by this change:

IDT Part Number	DSCC Part Number	Old Stepping	New Stepping
IDT54FCT573TDB	5962-9223801MRA	P	PB
IDT54FCT573ATDB	5962-9223802MRA	P	PB
IDT54FCT573CTDB	5962-9223803MRA	P	PB
IDT54FCT573TLB	5962-9223801M2A	P	PB
IDT54FCT573ATLB	5962-9223802M2A	P	PB
IDT54FCT573CTLB	5962-9223803M2A	P	PB

Conversion Schedule:

Die Revision

PB Stepping

Sample Availability:

Now

Production Shipment:

June 24, 2004



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Qualification Plans: Following reliability tests were performed on the Mil-Grade PB Stepping.
The qualification results are as follow:

Test Description	Test Method	Required Sample/ # Fails	PB Stepping (Mil-Grade)
Operating Life Test: Dynamic 184 hrs @ 150°C (Mil-Grade)	Mil-Std 883 Method 1005	116/0	116/0
ESD Human Body Model	Mil-Std 883 Method 3015	3/0	2,500V
Latch up: (Tested to 1.5X Vcc)	EIA/JESD STD-78	6/0	6/0